

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Xinagfei Chen	08/15/2008
RECEIVING PARTY DATA	
Name:	Nanjing University
Street Address:	No. 22 Hankou Road
City:	Nanjing, Jiangsu
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12281765
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Total Attachments: 1 source=TIY-108assign#page1.tif	

OP \$40.00 12281765

ASSIGNMENT

WHEREAS, I/WE:

XIANGFEI CHEN, residing in
No. 22 Hankou Road, Nanjing, Jiangsu 210093, China

has invented certain new and useful improvements in the following:

Distributed Feedback Semiconductor Laser Based on Reconstruction-Equivalent-Chirp Technology and the Manufacture Method of the Same

for which a United States patent application therefor has been executed on 8/15/2008,
U.S. Patent Application No.: 12281765;

WHEREAS,

NANJING UNIVERSITY

(hereinafter referred to as the Assignee), a body having a place of business at **No. 22 Hankou Road, Nanjing, Jiangsu 210093, China** and corporate powers under the laws of **China**, desires to acquire the entire right, title and interest in said application and invention, and to any United States and foreign patents to be obtained therefor.

NOW THEREFORE, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to Assignee, its successors and assigns, the entire right, title and interest in said application and inventions therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said application, I/we hereby agree that Assignee may apply for foreign Letters Patent on said inventions, and I/we hereby agree to timely execute all papers necessary in connection with said United States and foreign Letters Patent applications when called upon to do so by Assignee.

I/we hereby covenant that I/we have the full and lawful right to convey the entire right, title, and interest herein assigned, and that I/we have not entered and will not enter into any agreement in conflict herewith.

I/we hereby request the Commissioner for Patents to issue any Letters Patent granted upon the inventions set forth in said application to Assignee, its successors and assigns.

Date: <u>Aug 15, 2008</u>	<u>Xiangfei Chen</u> XIANGFEI CHEN
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